TE Internal #: 5-2364427-4

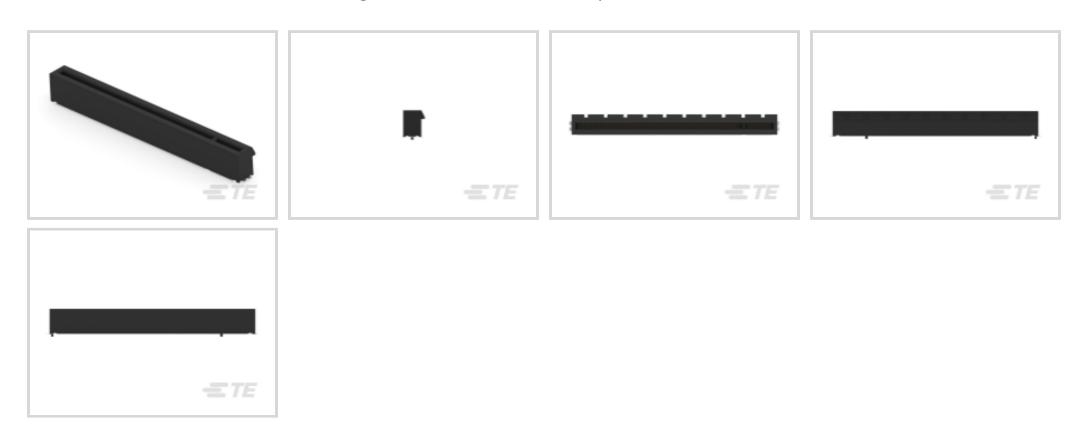
Board-to-Board, 164 Position, 1 mm [.04 in] Centerline, Vertical, Black, Height 11.25 mm [.44 in], Width 8.2 mm [.32 in], PCI & PCI

Express Connectors

View on TE.com >



Connectors > PCB Connectors > Card Edge Connectors > PCI & PCI Express Connectors



Connector System: Board-to-Board

Number of Positions: 164

PCI Generation: 5

Centerline (Pitch): 1 mm [ .04 in ]

Termination Post & Tail Length: 1.1 mm [.043 in]

# **Features**

# Product Type Features

Connector & Contact Terminates To	Printed Circuit Board
Connector System	Board-to-Board
Sealable	No
Configuration Features	
Number of Positions	164
PCB Mount Orientation	Vertical
Ejector	Without
Body Features	
Primary Product Color	Black
Contact Features	
Contact Current Rating (Max)	1.1 A
	30 μin

Termination Method to PCB	Surface Mount
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Termination Post & Tail Length	1.1 mm[.043 in]
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#### Mechanical Attachment

PCB Mount Retention Type	Metal Hold-Down
Connector Mounting Type	Board Mount

## **Housing Features**

Centerline (Pitch)	1 mm[.04 in]
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#### **Dimensions**

Connector Height	11.25 mm[.44 in]
Connector Width	8.2 mm[.32 in]

### **Usage Conditions**

Operating Temperature Range	-40 - 85 °C[-40 - 185 °F]

# Operation/Application

Circuit Application	High Speed Data
Industry Standards	
PCI Generation	5

# **Product Compliance**

For compliance documentation, visit the product page on TE.com>

EU RoHS Directive 2011/65/EU	Compliant
EU ELV Directive 2000/53/EC	Compliant
China RoHS 2 Directive MIIT Order No 32, 2016	No Restricted Materials Above Threshold
EU REACH Regulation (EC) No. 1907/2006	Current ECHA Candidate List: JUNE 2024 (241) Candidate List Declared Against: JUNE 2024 (241) Does not contain REACH SVHC
Halogen Content	Low Halogen - Br, Cl, F, I < 900 ppm per homogenous material. Also BFR/CFR/PVC Free
Solder Process Capability	Not reviewed for solder process capability

#### Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products



will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: https://echa.europa.eu/guidance-documents/guidance-on-reach

# Compatible Parts



# Customers Also Bought











TE Part #2007198-1 SFP+ 1x1 Cage Assembly, Press-



TE Part #1-2324271-3 RIGHT SEGMENT LGA4189-4 SOCKETP4 FOR ODM



TE Part #1775485-3 BATTERY HOLDER, 3.6MM, HIGH STANDOFF TE Part #2-2007394-6 SFP+ ASSY2x4 EMI Spg Inner LP Sn Enhance

TE Part #8-2355644-1
DDR5 DIMM SMT\_blue hsg&blue latch

## **Documents**

## **Product Drawings**



## PCIE GEN5 CON,SMT,164P,30u Au,MYLAR,HT

English

### **CAD Files**

**Customer View Model** 

ENG\_CVM\_CVM\_5-2364427-4\_A.3d\_igs.zip

English

**Customer View Model** 

ENG\_CVM\_CVM\_5-2364427-4\_A.3d\_stp.zip

English

**Customer View Model** 

ENG\_CVM\_CVM\_5-2364427-4\_A.2d\_dxf.zip

English

3D PDF

3D

By downloading the CAD file I accept and agree to the **Terms and Conditions** of use.

# **Product Specifications**

**Application Specification** 

English